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Januray 2014

# FQD11P06 / FQU11P06

# P-Channel QFET® MOSFET

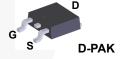
-60 V, -9.4 A, 185 mΩ

# **Description**

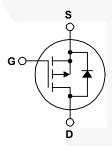
This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance • Low Crss (Typ. 45 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications...

#### **Features**

- -9.4 A, -60 V,  $R_{DS(on)}$  = 185 m $\Omega$  (Max.) @  $V_{GS}$  = -10 V,  $I_D = -4.7 A$
- Low Gate Charge (Typ. 13 nC)







# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQD11P06TM / FQU11P06TU	Unit
V <sub>DSS</sub>	Drain-Source Voltage		-60	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		-9.4	Α
	- Continuous (T <sub>C</sub> = 100°C)		-5.95	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	-37.6	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		160	mJ
I <sub>AR</sub>	Avalanche Current (f		-9.4	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1		3.8	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		-7.0	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		2.5	W
	Power Dissipation (T <sub>C</sub> = 25°C)		38	W
	- Derate above 25°C		0.3	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering, 1/8" from case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	FQD11P06TM / FQU11P06TU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max. 3.28		
В	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	110	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in <sup>2</sup> Pad of 2-oz Copper), Max.	50	1

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQD11P06TM	FQD11P06	D-PAK	Tape and Reel	330 mm	16 mm	2500 units
FQU11P06TU	FQU11P06	I-PAK	Tube	N/A	N/A	70 units

# **Flectrical Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 μA, Referenced to 25°C		-0.07		V/°C
I <sub>DSS</sub>	Zero Oeto Valtono Busin Organia	V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V		-	-1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -48 V, T <sub>C</sub> = 125°C			-10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V			-100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-2.0		-4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -4.7 A		0.15	0.185	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -30 V, I <sub>D</sub> = -4.7 A		4.9		S
Dynam	ic Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$		420	550	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		195	250	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			45	60	pF
Switch	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = -30 V, I <sub>D</sub> = -5.7 A,		6.5	25	ns
t <sub>r</sub>	Turn-On Rise Time	$R_{G} = 25 \Omega$		40	90	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	NG - 20 32		15	40	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		45	100	ns
Qg	Total Gate Charge	V <sub>DS</sub> = -48 V, I <sub>D</sub> = -11.4 A,		13	17	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -10 V	/	2.0		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)		6.3		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings			/	
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				-9.4	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current			-	-37.6	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -9.4 A		-	-4.0	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -11.4 A,		83	//	ns
भा						

- **Notes:** 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 2.1 mH,  $I_{AS}$  = -9.4 A,  $V_{DD}$  = -25 V,  $R_G$  = 25  $\Omega$ , starting  $T_J$  = 25°C. 3.  $I_{SD}$  ≤ -11.4 A, di/dt ≤ 300 A/ $\mu$ s,  $V_{DD}$  ≤ BV $_{DSS}$ , starting  $T_J$  = 25°C. 4. Essentially independent of operating temperature.

# **Typical Characteristics**

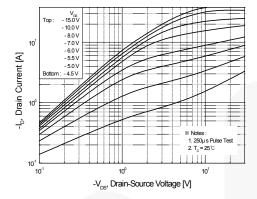


Figure 1. On-Region Characteristics

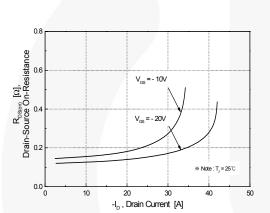


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

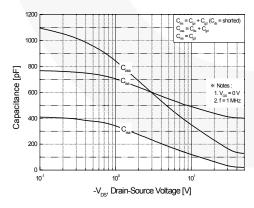


Figure 5. Capacitance Characteristics

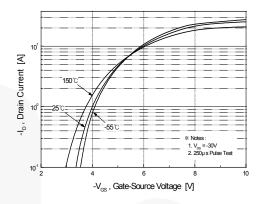


Figure 2. Transfer Characteristics

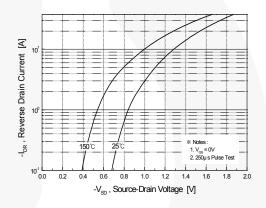


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

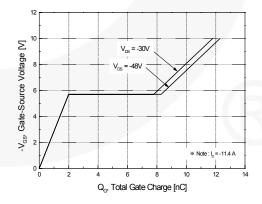


Figure 6. Gate Charge Characteristics

# 12 (Normalized) 1.1 (Normalized) 1.0 (Normalized) 1.1 (No

Typical Characteristics (Continued)

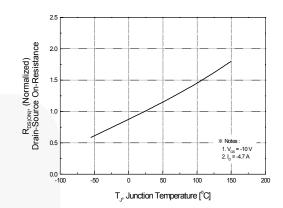
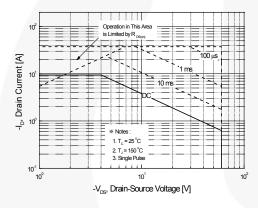


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



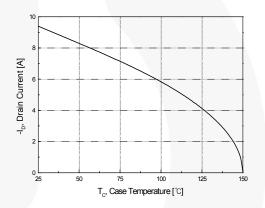


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

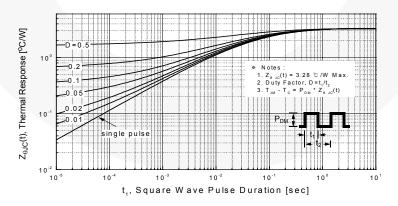


Figure 11. Transient Thermal Response Curve

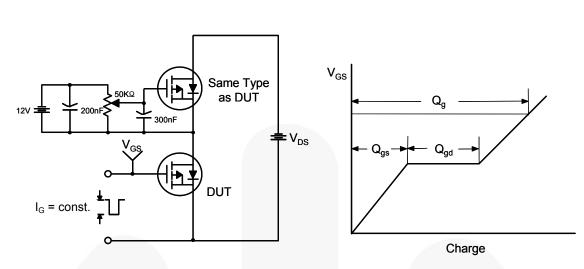


Figure 12. Gate Charge Test Circuit & Waveform

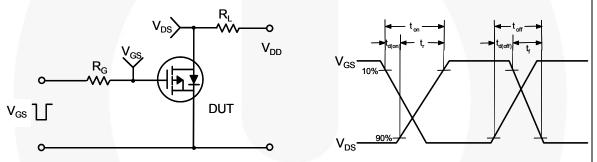


Figure 13. Resistive Switching Test Circuit & Waveforms

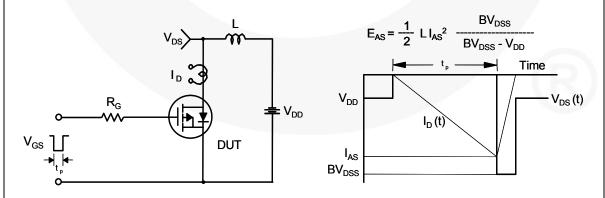
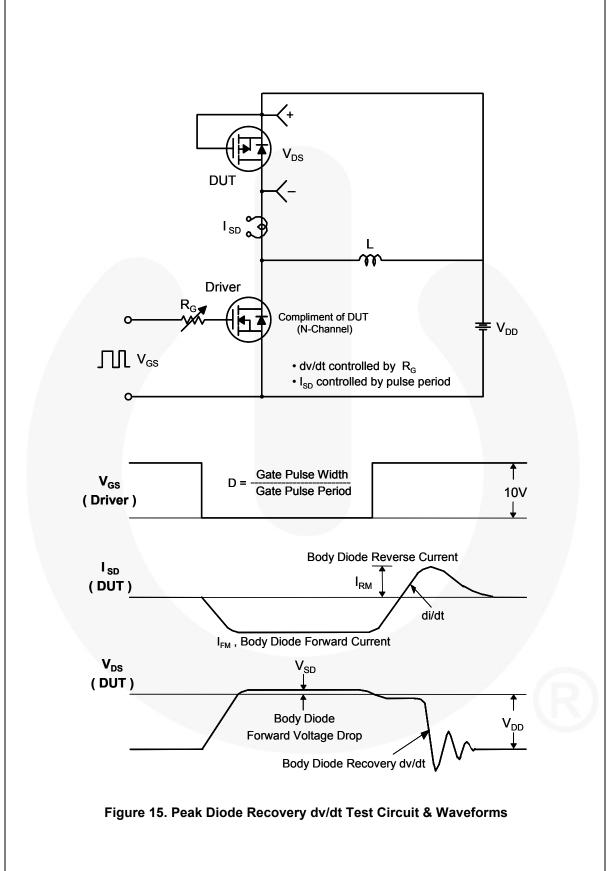


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



## -5.55 MIN→ 1.27 6.22 5.97 6.50 MIN -1.02 MAX Ċ 2 (0.59)0.89 2.29 2.28 ⊕ 0.25 A A C 4.57 LAND PATTERN RECOMMENDATION 2.39 SEE 2.18 4.32 MIN NOTE D 0.58 0.45 5.21 MIN 10.41 9.40 SEE DETAIL A △ 0.10 B 0.51 GAGE PLANE NOTES: UNLESS OTHERWISE SPECIFIED THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA. ALL DIMENSIONS ARE IN MILLIMETERS. 10 (1.54)DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009. SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION. PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL. .78 0.127 MAX DIMENSIONS ARE EXCLUSSIVE OF BURSS, MOLD FLASH AND TIE BAR EXTRUSIONS. SEATING PLANE (2.90)LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD DETAIL TO228P991X239-3N. (ROTATED -90°) SCALE: 12X DRAWING NUMBER AND REVISION: MKT-T0252A03REV9. FAIRCHILD SEMICONDUCTOR.

Figure 16. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

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**Mechanical Dimensions** 

# **Mechanical Dimensions** C 9.65 8.90 (0.60) -2.29 ◆ 0.25M AM C 3 PLCS NOTES: UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS.

- B) THIS PACKAGE CONFORMS TO JEDEC, TO-251, ISSUE C, VARIATION AA, DATED SEP 1988.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

Figure 17. TO251 (I-PAK), Molded, 3-Lead

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